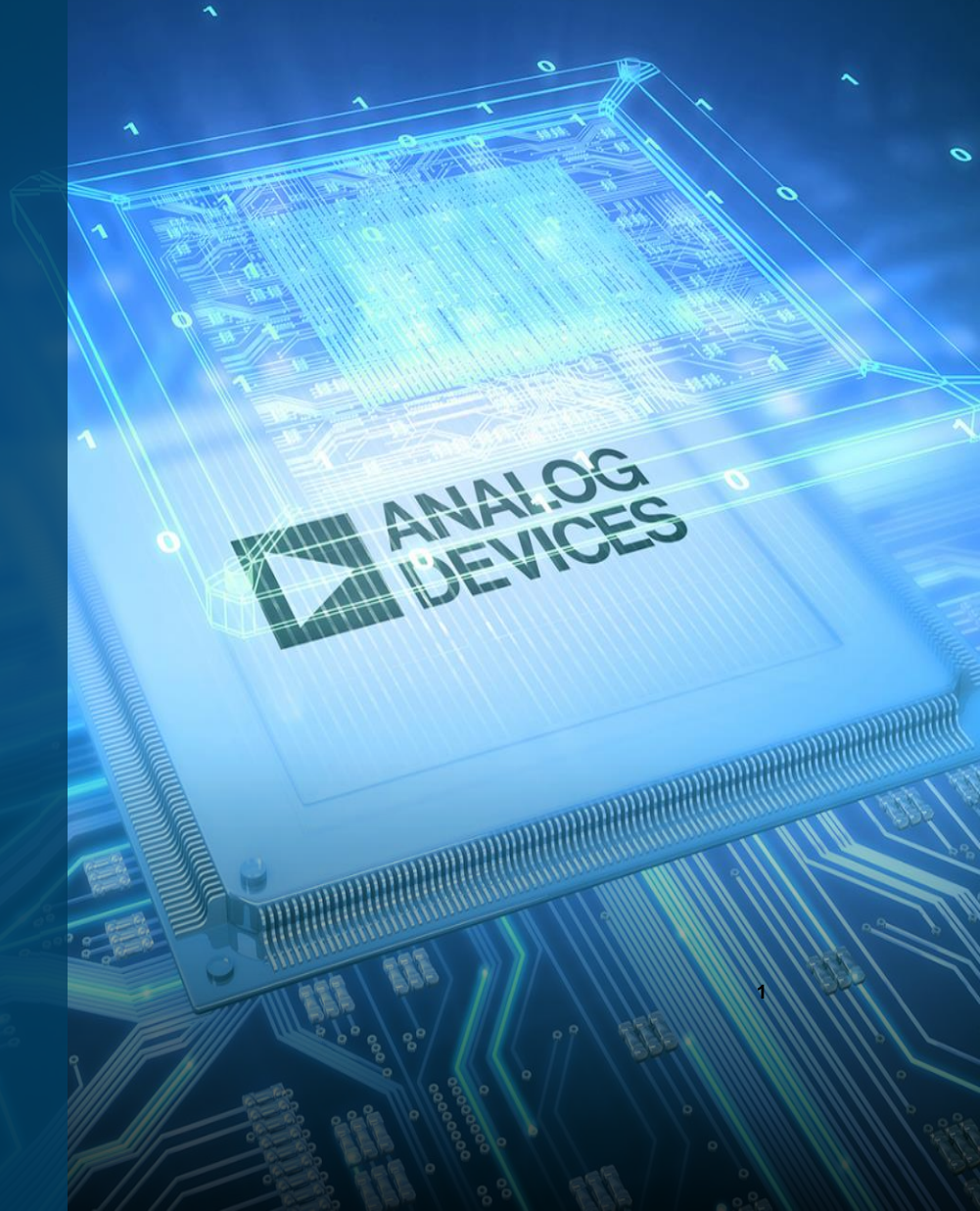




AHEAD OF WHAT'S POSSIBLE™

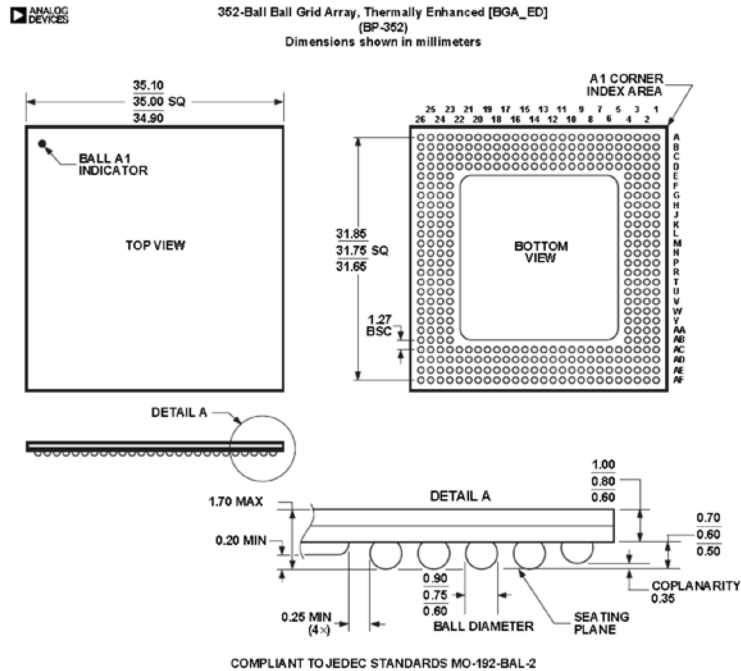
ADN4605 Assembly Site Transfer and Data Sheet Revision_PCN



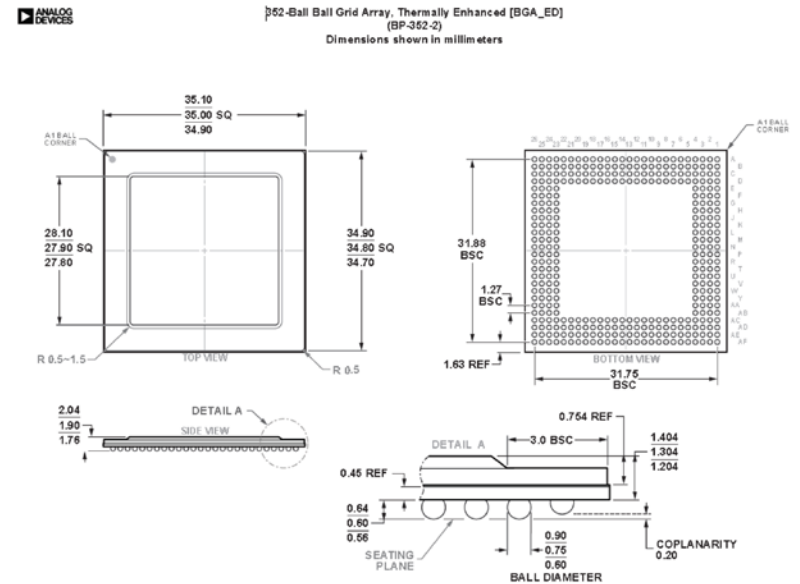
DATE: 07-27-2019

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Change #1- Package Outline Drawing



Current POD → BP-352
1.7mm max height



New POD → BP-352-2
2.04mm max height

Change #2 – Die Interconnect

- ▶ Current package uses wire bonded die
- ▶ New package uses flip chip die with solder bumps

Change #3 Assembly Site

- ▶ New assembly site is STATS ChipPAC Korea

Change #4- Data Sheet Change

- ▶ Data sheet rev change from RevA to RevB.
- ▶ On page 2 under Revision History RevB changes were added.
- ▶ On page 4 Electrical Characteristics – Removed thermal characteristics section and note 2.
- ▶ On page 7 Absolute Maximum Ratings – Changed Internal Power Dissipation¹ rating from 8.4W to 11.5W
- ▶ On page 7 Absolute Maximum Ratings under NOTES1 – Change $\theta_{JA} = 9.2^{\circ} \text{ C/W TO } 8.5^{\circ} \text{ C/W}$.
- ▶ On page 7 added Thermal Resistance Section.
- ▶ On page 55 Changed package outline drawing.
- ▶ On page 55 Ordering Guide – Changed package Option BP-352 to BP-352-2.